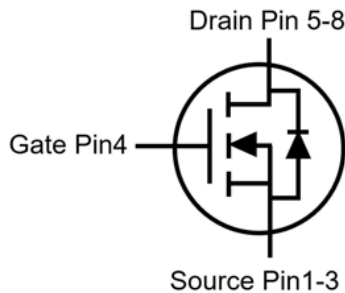
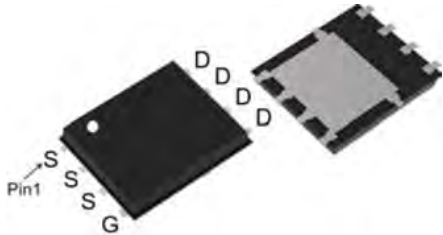


## SGT N-channel Power MOSFET

### MTR5R8N06SD PDFN5x6



$V_{DS}$	60	V
$R_{DS(on),TYP}@ V_{GS}=10V}$	4.6	m $\Omega$
$I_D$	90	A

### Features

- 1、 Low on – resistance
- 2、 High power package (PDFN5X6)
- 3、 SGT N-channel Power MOSFET
- 4、 Halogen free

### Applications

- 1、 Load Switch for Portable Devices
- 2、 DC/DC Converter

### Maximum ratings, at $T_A = 25^\circ\text{C}$ , unless otherwise specified

Symbol	Parameter	Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage	60	V
$V_{GS}$	Gate-Source voltage	$\pm 20$	V
$I_{AS}$	Avalanche Current	$T_C = 25^\circ\text{C}$	32 A
$I_D$	Continuous drain current @ $V_{GS}=10V$	$T_C = 25^\circ\text{C}$	90 A
		$T_C = 100^\circ\text{C}$	57 A
$I_{DM}$	Pulse drain current tested ①	$T_C = 25^\circ\text{C}$	269 A
$E_{AS}$	Avalanche energy, single pulsed ②	51	mJ
$P_D$	Maximum power dissipation	$T_C = 25^\circ\text{C}$	83 W
$T_{STG}, T_J$	Storage and Junction Temperature Range	-55 to 150	$^\circ\text{C}$

## Thermal Characteristics

Symbol	Parameter	Rating	Unit
R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case	1.2	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient	45	°C/W

## Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
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Static Electrical Characteristics @T<sub>j</sub>=25°C (unless otherwise stated)

V(BR)DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	60	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =48V, V <sub>GS</sub> =0V	--	--	1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.2	1.7	2.5	V
R <sub>DS(on)</sub>	Drain-Source On-State Resistance ④	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	--	4.6	5.8	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =15A	--	6.0	7.5	mΩ
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> = 5V, I <sub>D</sub> = 20A	--	85	--	S

## Dynamic Electrical Characteristics@T<sub>j</sub> = 25°C (unless otherwise stated)

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V , f=1MHz	--	2122	--	pF
C <sub>oss</sub>	Output Capacitance		--	440	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	4.4	--	pF
R <sub>g</sub>	Gate Resistance	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 0V, f = 1MHz	--	1.4	--	Ω
Q <sub>g</sub> (10V)	Total Gate Charge	V <sub>DS</sub> =30V, I <sub>D</sub> =20A , V <sub>GS</sub> =10V	--	31	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	4.8	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	5.4	--	nC

## Switching Characteristics

Td(on)	Turn-on Delay Time	V <sub>DD</sub> =30V, V <sub>GS</sub> =10V R <sub>L</sub> =1.5Ω, R <sub>G</sub> =6Ω,	--	8.0	--	ns
Tr	Turn-on Rise Time		--	5.1	--	ns
Td(off)	Turn-Off Delay Time		--	38	--	ns
Tf	Turn-Off Fall Time		--	14.8	--	ns

## Source- Drain Diode Characteristics@ T<sub>j</sub> = 25°C (unless otherwise stated)

VSD	Forward on voltage	I <sub>s</sub> =1A, V <sub>GS</sub> =0V	--	0.7	1.0	V
Trr	Reverse Recovery Time	I <sub>F</sub> =20A	--	37	--	ns
Qrr	Reverse Recovery Charge	di/dt=100A/μs	--	43	--	nC

- NOTE: ① Repetitive rating; pulse width limited by max junction temperature.  
 ② Limited by T<sub>Jmax</sub>, starting T<sub>J</sub> = 25°C, L = 100μH, V<sub>GS</sub> = 10V, V<sub>DS</sub> = 30V, Part not recommended for use above this value  
 ③ The power dissipation P<sub>DSM</sub> is based on R<sub>θJA</sub> and the maximum allowed junction temperature of 150°C.  
 ④ Pulse width ≤ 380μs; duty cycle ≤ 2%.

## Typical Characteristics

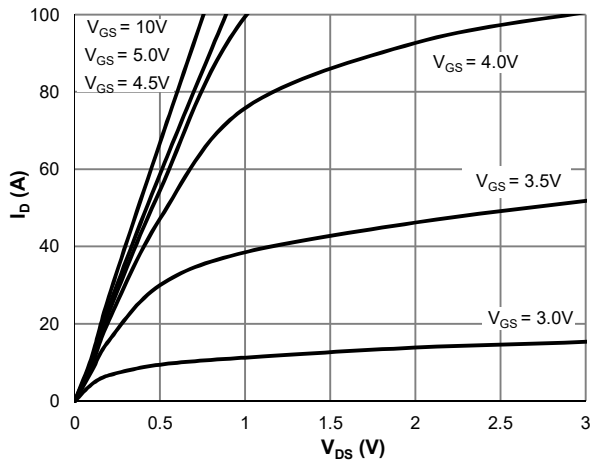


Figure 1: Saturation Characteristics

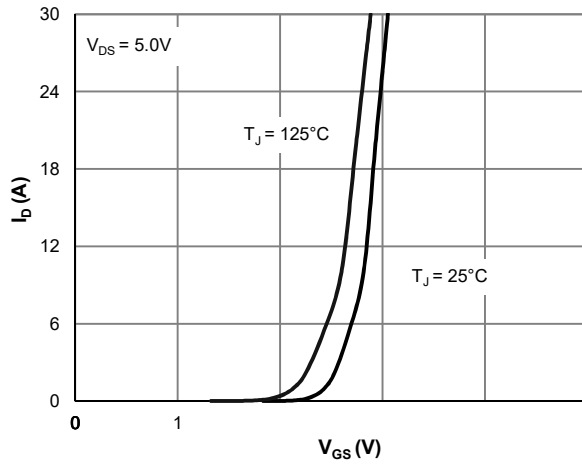


Figure 2: Transfer Characteristics

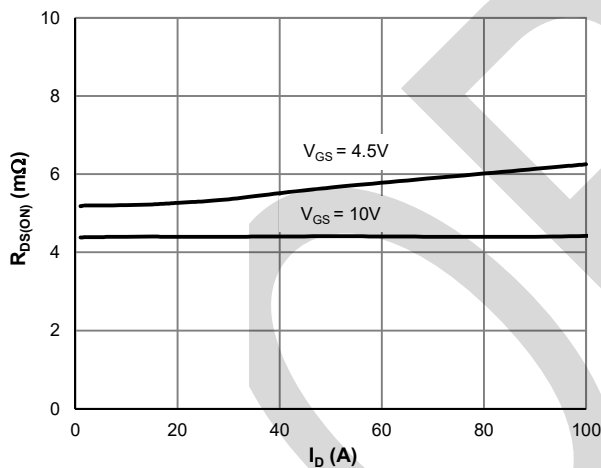


Figure 3:  $R_{DS(ON)}$  vs. Drain Current

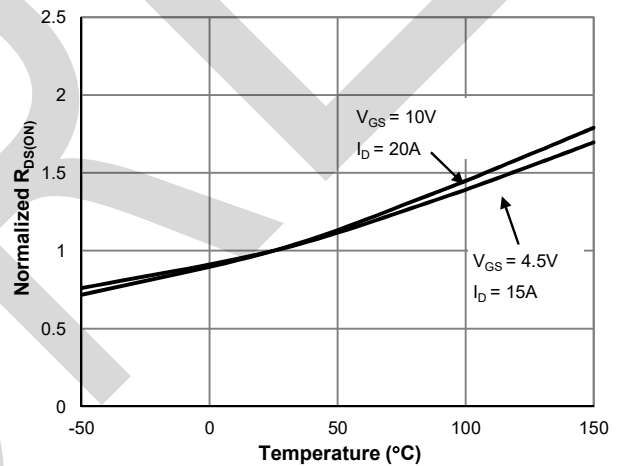


Figure 4:  $R_{DS(ON)}$  vs. Junction Temperature

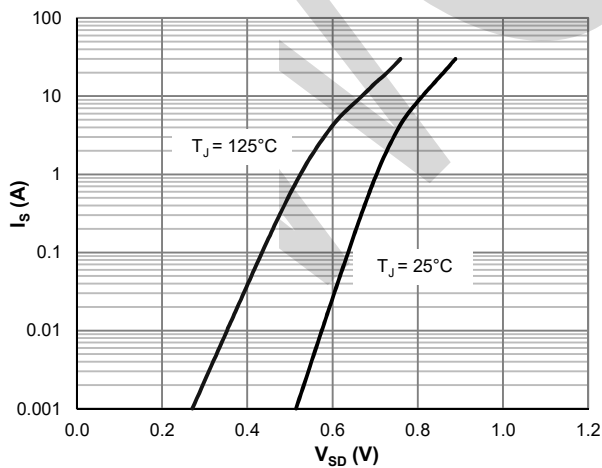


Figure 5: Body-Diode Characteristics

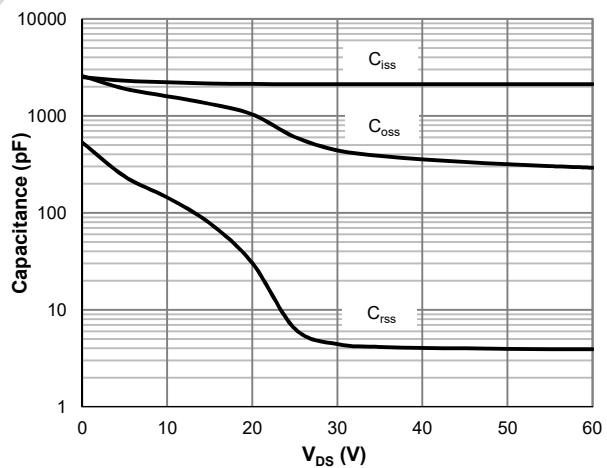


Figure 6: Capacitance Characteristics

## Typical Characteristics

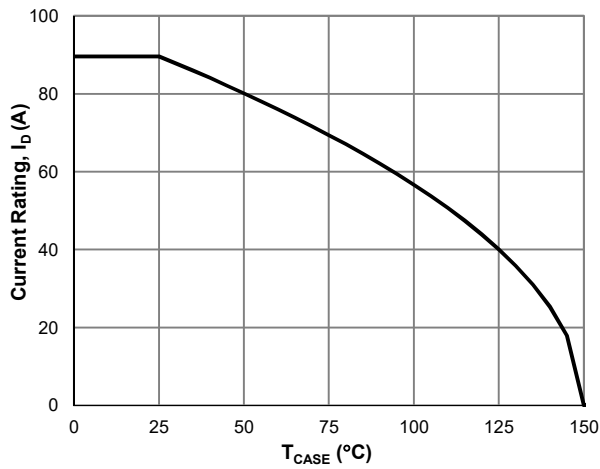


Figure 7: Current De-rating

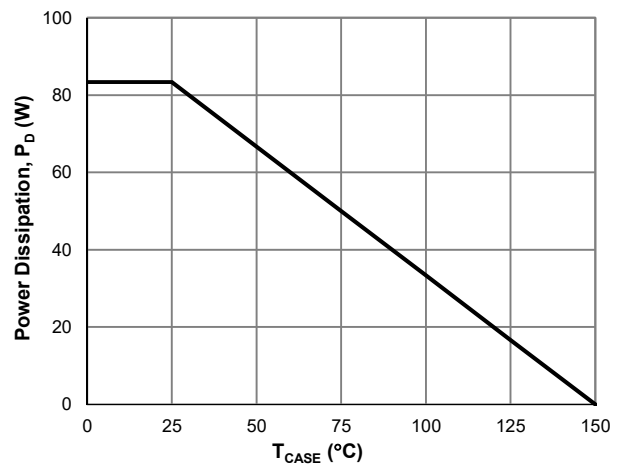


Figure 8: Power De-rating

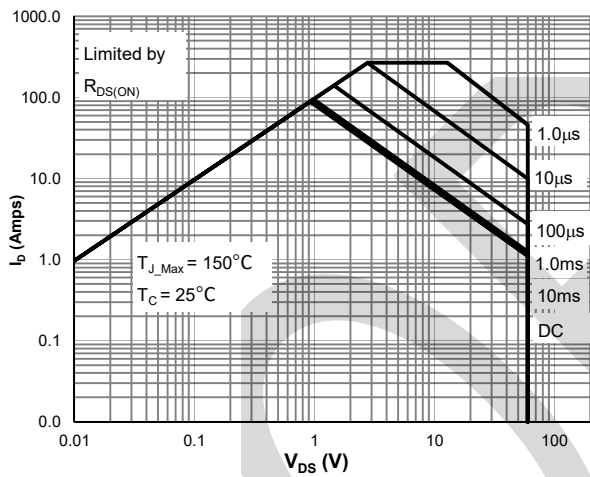


Figure 9: Maximum Safe Operating Area

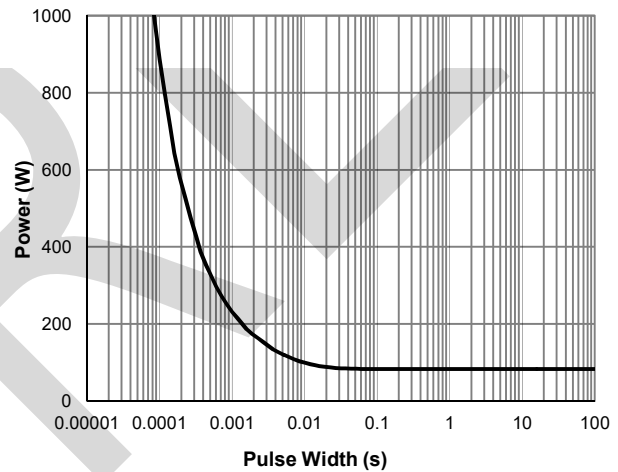


Figure 10: Single Pulse Power Rating, Junction-to-Case

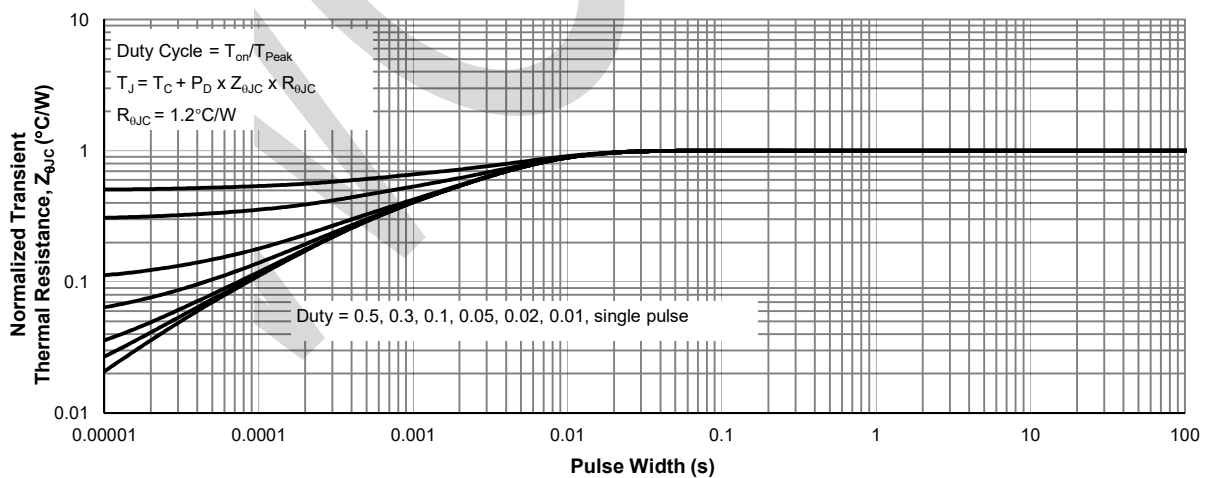
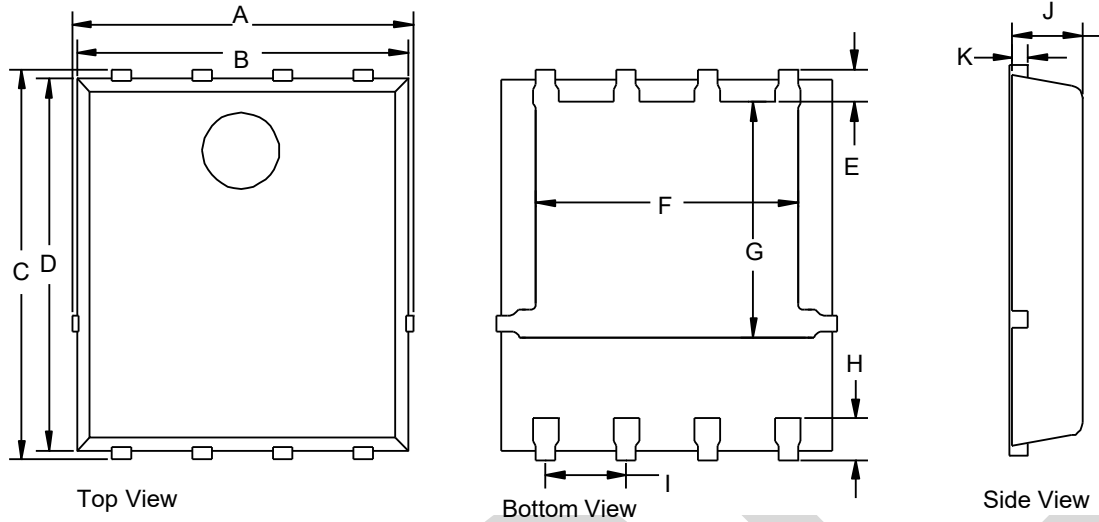


Figure 11: Normalized Maximum Transient Thermal Impedance

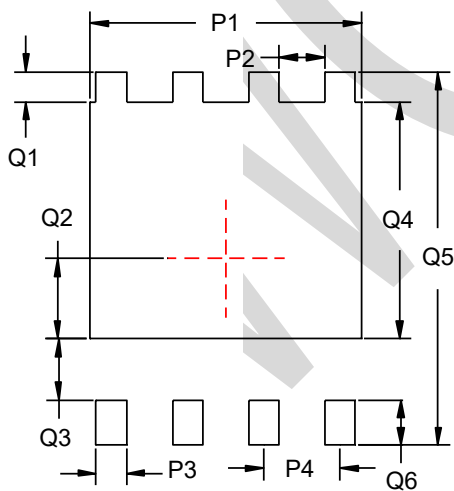
## PACKAGE OUTLINE DIMENSIONS



## PDFN5x6 mechanical data

UNIT		A	B	C	D	E	F	G	H	I	J	K
mm	min	4.90	4.8	5.90	5.66	0.60	3.90	3.30	0.53	1.27	0.9	0.254
	max	5.55	5.4	6.35	6.06		4.32	3.92	0.76		1.2	
mil	min	192.9	188.9	232.3	222.8	23.6	153.5	129.9	20.8	50.0	35.4	10.0
	max	218.5	212.6	250.0	238.6		170.1	154.3	29.9		47.2	

## PDFN5x6 Suggested Pad Layout



UNIT		P1	P2	P3	P4	Q1
mm	min	4.52	0.76	0.51	1.27	0.50
mil	min	177.9	29.9	20.07	50.0	20.0

UNIT		Q2	Q3	Q4	Q5	Q6
mm	min	1.34	1.02	3.97	6.25	0.76
mil	min	52.75	40.15	156.30	246.06	29.92